



Material Content Data Sheet



Halogen-Free

Sales Product Name	BFP 460 H6327	Issued	19. May 2021
MA#	MA001309748		
Package	PG-SOT343-4-1	Weight*	6.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.01		69	
	noble metal	gold	7440-57-5	0.002	0.03		268	
	inorganic material	silicon	7440-21-3	0.016	0.23	0.27	2312	2649
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		499	
	non noble metal	chromium	7440-47-3	0.010	0.15		1497	
	non noble metal	copper	7440-50-8	3.347	49.69	49.90	496953	499049
wire	noble metal	gold	7440-57-5	0.013	0.19	0.19	1942	1942
encapsulation	organic material	carbon black	1333-86-4	0.031	0.46		4573	
	plastics	epoxy resin	-	0.662	9.83		98319	
	inorganic material	silicondioxide	60676-86-0	2.387	35.44	45.73	354405	457297
leadfinish	non noble metal	tin	7440-31-5	0.199	2.96	2.96	29579	29579
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9484	9484
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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